PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#2

JC564 U.S. PTO
09/538684
03/30/00

In re Application of:

Kinsman et al.

Serial No.: Not yet assigned

Filed: March 30, 2000

For: VARIED-THICKNESS HEAT SINK FOR INTEGRATED CIRCUIT (IC) PACKAGES AND METHOD OF FABRICATING IC PACKAGES

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 3056.1US (96-803.1)

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INFORMATION DISCLOSURE STATEMENT

Box PATENT APPLICATION
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The present application is a divisional of application Serial No. 08/887,381, filed July 2, 1997, pending. This application is related to a co-pending application entitled "LEAD FRAME ASSEMBLIES WITH VOLTAGE REFERENCE PLANE AND IC PACKAGES INCLUDING SAME," filed July 2, 1997, having Serial No. 08/888,336, now U.S. Patent 5,955,777, issued September 21, 1999, and commonly assigned with the present application.

Pursuant to M.P.E.P. 2001.06(b), the Examiner is respectfully requested to consider the information of record in the prior applications, and to confirm in the first Office Action on the merits that such art has in fact been reviewed. A PTO-1449 form listing all of the information of record in the prior applications is enclosed herewith.

This Information Disclosure Statement is filed within three (3) months of the filing date of the above-identified application, and no certification pursuant to 37 C.F.R. § 1.97(c) or a fee pursuant to 37 C.F.R. 1.17(p) is required.

Respectfully submitted,

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Date: March 30, 2000
SEW/jml
Enclosure: Form PTO-1449

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